



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-12V	8mΩ@-4.5V	-27A
	9mΩ@-3.7V	
	10mΩ@-2.5V	
	15mΩ@-1.8V	

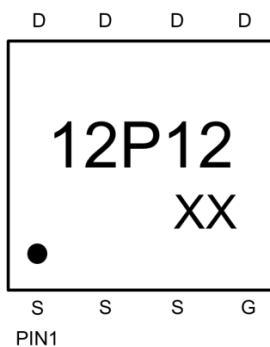
Feature

- High cell density trenching P-ch MOSFETs
- Super low gate charge
- Advanced high cell density Trench technology

Application

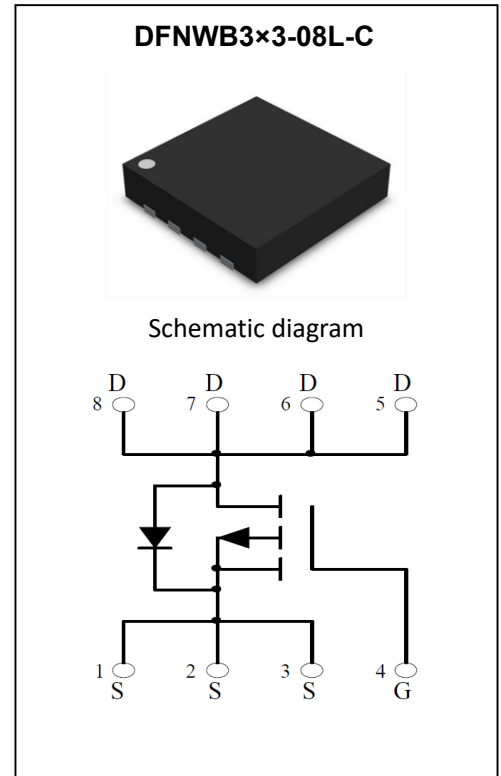
- Battery protection applications
- Load switch

MARKING:



12P12= Device code
 Solid dot=Pin1 indicator
 XX=Date Code

PIN1



ABSOLUTE MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-12	V
Gate-Source Voltage	V_{GS}	± 8	V
Continuous Drain Current ¹	I_D	-27	A
Pulsed Drain Current ¹	I_{DM}	-81	A
Power Dissipation ²	P_D	3	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}\text{C}$

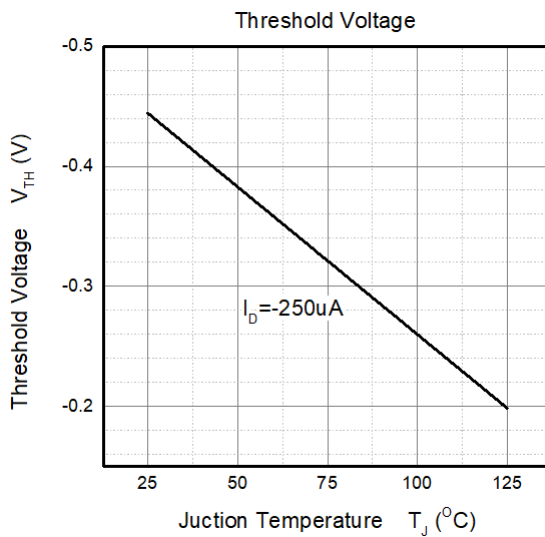
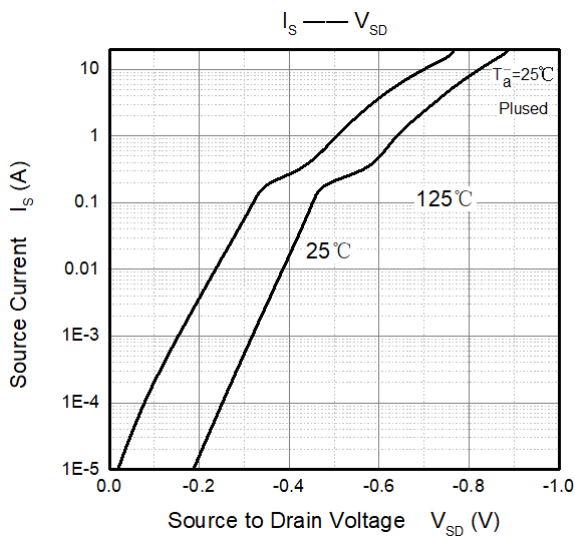
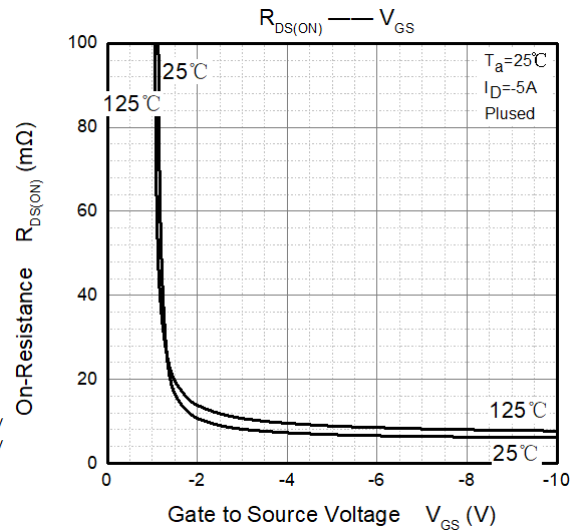
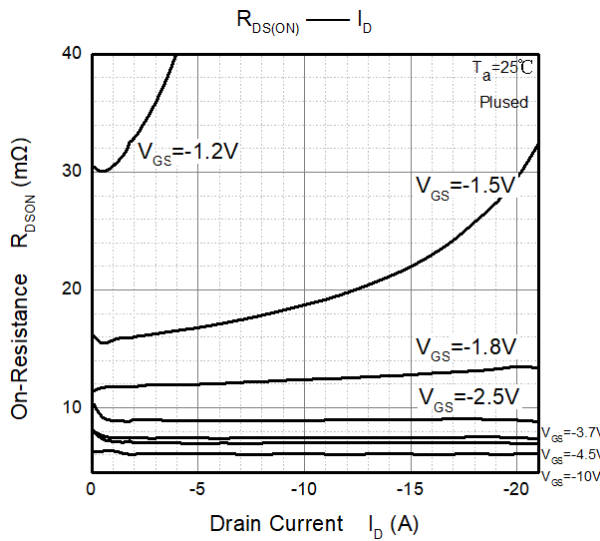
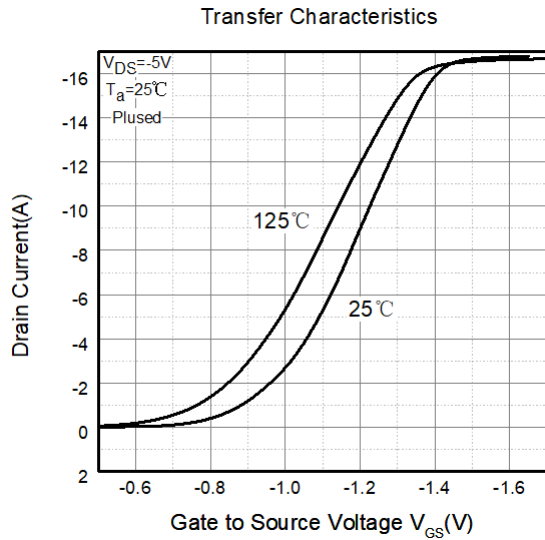
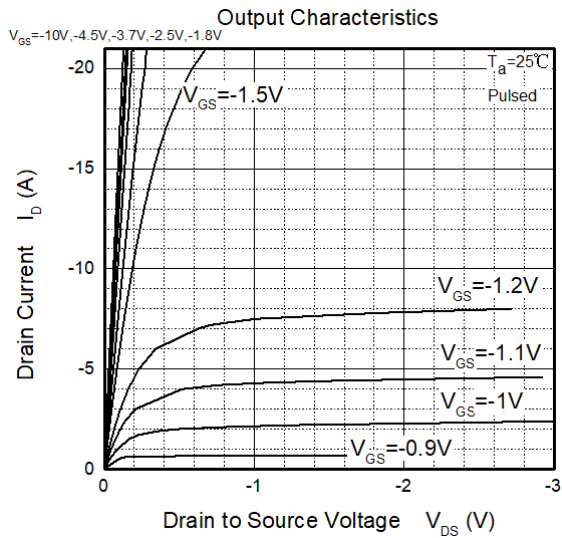
MOSFET ELECTRICAL CHARACTERISTICS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-12	-19	-20	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = -12V, V_{GS} = 0V$			-1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 8V, V_{DS} = 0V$			± 100	nA
Gate threshold voltage ³	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$			-1	V
Drain-source on-resistance ³	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -10A$		8	12	m Ω
		$V_{GS} = -3.7V, I_D = -10A$		9	13	
		$V_{GS} = -2.5V, I_D = -8A$		10	14	
		$V_{GS} = -1.8V, I_D = -6A$		15	19	
Forward transconductance ³	g_{FS}	$V_{DS} = -5V, I_D = -10A$	5			S
Dynamic characteristics⁴						
Input Capacitance	C_{iss}	$V_{DS} = -6V, V_{GS} = 0V, f = 1MHz$		3850		pF
Output Capacitance	C_{oss}			970		
Reverse Transfer Capacitance	C_{rss}			1000		
Gate resistance	R_g	$f = 1MHz$			15	Ω
Total Gate Charge	Q_g	$V_{DS} = -6V, V_{GS} = -4.5V, I_D = -5A$		42		nC
Gate-Source Charge	Q_{gs}			6.9		
Gate-Drain Charge	Q_{gd}			10.8		
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -6V, V_{GEN} = -4.5V, I_D = -4A$ $R_L = 6\Omega, R_{GEN} = 1\Omega$		20		Ns
Turn-on rise time	t_r			15		
Turn-off delay time	$t_{d(off)}$			45		
Turn-off fall time	t_f			22		
Source-Drain Diode characteristics						
Diode forward current ⁵	I_S	$T_C = 25^\circ\text{C}$			-27	A
Diode pulsed forward current ⁵	I_{SM}				-80	A
Diode Forward voltage ³	V_{DS}	$V_{GS} = 0V, I_S = -10A$		-0.8	-1.2	V

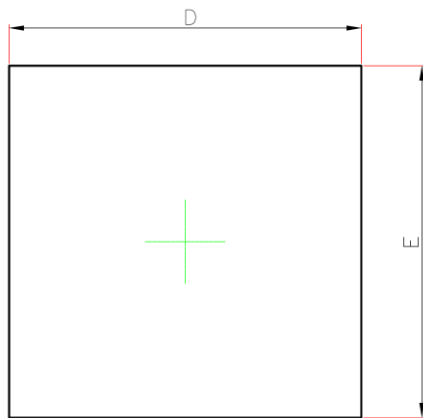
Notes:

1. Device mounted on FR-4 substrate board, with minimum recommended pad layout, single side.
2. The power dissipation is limited by 150°C junction temperature
3. Pulse Test : Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.
5. The data is theoretically the same as I_D , in real applications, should be limited by total power dissipation.

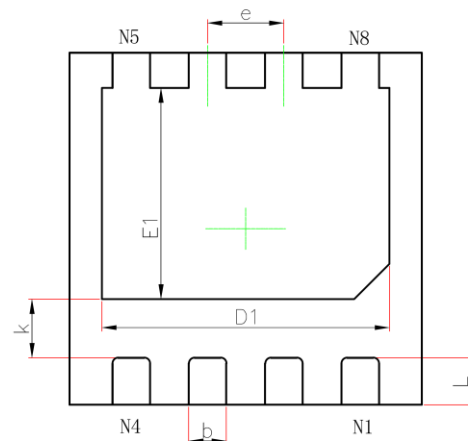
Typical Electrical and Thermal Characteristics



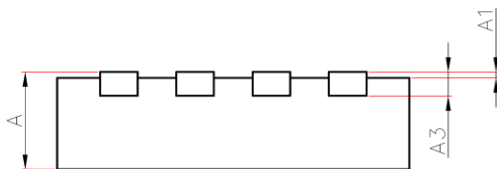
DFNWB3x3-08L-C Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

单击下面可查看定价，库存，交付和生命周期等信息

[>>GP\(格瑞宝\)](#)